



**3875**

May 2012

**PRODUCT DESCRIPTION**

3875 provides the following product characteristics:

<b>Technology</b>	Acrylate
<b>Technology (Part B)</b>	Acrylate
<b>Appearance - Part A</b>	Pale yellow
<b>Appearance - Part B</b>	Pale blue
<b>Components</b>	Two-component
<b>Product Benefits</b>	<ul style="list-style-type: none"> <li>Thermally conductive</li> <li>Ease of use</li> </ul>
<b>Cure</b>	Room temperature
<b>Application</b>	Thermal management
<b>Typical Assembly Applications</b>	Transistors, Rectifiers, other power devices and computing applications such as memory chips, chipsets and graphic processor assembly

3875 bead-on-bead, thermally conductive adhesive is designed to thermally couple and structurally bond heatsinks to heat dissipating electronic components. It is formulated to cure when the two components come into contact with one another, requiring no primer or heat.

**TYPICAL PROPERTIES OF UNCURED MATERIAL**

**Part A Properties**

Viscosity, mPa·s (cP):	
@ Speed 2.5 rpm	65,000
@ Speed 20 rpm	32,000
Specific Gravity, g/cc	1.7
Flash Point - See MSDS	

**Part B Properties**

Viscosity, mPa·s (cP):	
@ Speed 2.5 rpm	190,000
@ Speed 20 rpm	90,000
Specific Gravity, g/cc	1.7
Flash Point - See MSDS	

**TYPICAL CURING PERFORMANCE**

**Fixture Time**

3 to 5 minutes @ 23°C , 50% RH

**Cure Schedule**

24 to 72 hours @ 23°C , 50% RH

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

**TYPICAL PROPERTIES OF CURED MATERIAL**

**Physical Properties**

Coefficient of Thermal Expansion , ppm/°C:	
Alpha 1	54
Alpha 2	141
Glass Transition Temperature (Tg), °C	28
Thermal Conductivity, ASTM D5470, W/(m-K)	1.75

**TYPICAL PERFORMANCE OF CURED MATERIAL**

**Shear Strength**

Die Shear Strength:	
6.35 X 6.35 mm (250 x 250 mil) die @ 25 °C, kg-f:	
Ni/Cu leadframe	60
Ceramic	63
Silicon	68
Mold Compound	34
Contaminated Mold Compound	22

**Tensile Shear Strength:**

Grit blasted steel	N/mm <sup>2</sup>	16
	(psi)	(2,400)
Aluminum	N/mm <sup>2</sup>	13
	(psi)	(1,900)

**TYPICAL ENVIRONMENTAL RESISTANCE**

The ability of 3875 to withstand exposure to a number of severe environments was determined by measuring the change in thermal resistance of a standard test piece.

In these tests, a TO-247 MOSFET was bonded to the subject substrate. The baseline thermal resistance was determined after the material had fully cured.

The numbers referenced below indicated the change in thermal resistance, measured at room temperature, after the test piece had been exposed to the referenced condition for the allotted time.

**Change in Thermal Resistance (% of Change)**

Thermal Exposure , 1,000 hours	
@ 25°C:	
Ceramic	4.5
Silicon	-7.6
Mold Compound	-0.3
Contaminated Mold Compound	4.4
@ 125°C:	
Ceramic	8.0
Silicon	-3.5
Mold Compound	-0.7
Contaminated Mold Compound	-4.1



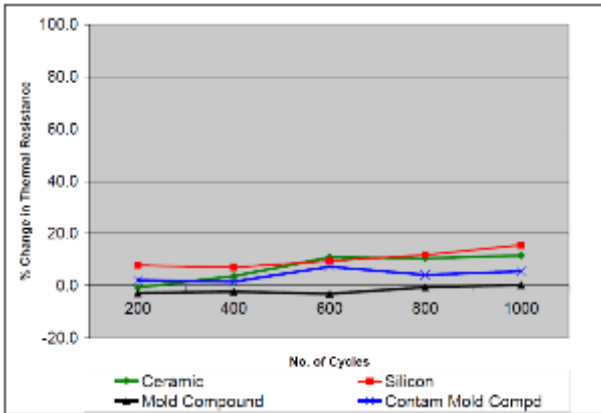
Moisture Resistance , 1,000 hrs @ 85°C/85% RH	
Ceramic	6.5
Silicon	2.5
Mold Compound	-7.1
Contaminated Mold Compound	0.1

Thermal Shock , 15 cycles @ -50 to +150°C (5 mins @ high temp + 5 mins @ low temp per cycle)

Ceramic	2.8
Silicon	0.0
Mold Compound	5.5
Contaminated Mold Compound	3.1

Thermal Cycling , -25 to +125°C temperature cycle, ramp 10°C per minute, 10 minute dwell

**Profile 1:**



**GENERAL INFORMATION**

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

**THAWING:**

- 3875 is packed to maintain temperatures between 5 to 10 °C during transit.
- DO NOT open the package before contents reach ambient temperature.
- A new package of material can be brought to ambient conditions by allowing container to stand at room temperature for 2 hours. Actual time required will vary with package size/volume.
- DO NOT attempt to thaw by applying additional heat.
- Do not loosen container lids, caps or covers. Allow syringe packs to equilibrate in tip down orientation..

**DIRECTIONS FOR USE**

- This two-part adhesive is designed to cure once the two components come into contact with each other. The material fixtures quickly and cures fully in 24-72 hours.
- For best performance bond surfaces should be clean and free from grease.
- Apply Part A to the component.
- Apply Part B to the heat sink.
- Apply enough material to each side so that there is enough material to cover at least 80% of the surface between the component and the heat sink and the material leaves a small fillet.

- Best thermal performance is obtained by using a ratio as close to 50:50 as possible .
- Place the heat sink on top of the component insuring that the beads of material overlap.
- Secure the assembly and wait for the adhesive to fixture (approx 5 minutes) before further handling.

**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

**Storage**

Store in original, tightly covered containers in clean, dry areas. Storage information may be indicated on the product container labeling.

**Optimal Storage: 5 to 10°C. Storage below 5°C or above 10°C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Conversions**

- (°C x 1.8) + 32 = °F
- kV/mm x 25.4 = V/mil
- mm / 25.4 = inches
- N x 0.225 = lb
- N/mm x 5.71 = lb/in
- N/mm<sup>2</sup> x 145 = psi
- MPa x 145 = psi
- N·m x 8.851 = lb·in
- N·m x 0.738 = lb·ft
- N·mm x 0.142 = oz·in
- mPa·s = cP

**Note**

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation and its affiliates ("Henkel") specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel products. Henkel specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data

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Americas  
+1.888.943.6535

Europe  
+44.1442.278.000

Asia  
+86.21.3898.4800

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